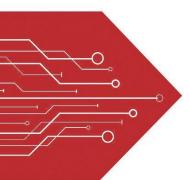
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Product data sheet

www.msksemi.com







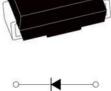
FEATURES

- → The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
 Built-in strain relief, ideal for automated placement
- → High forward surge current capability
 → High temperature soldering guaranteed:
- 250°C/10 seconds at terminals



MECHANICAL DATA

Case: JEDEC DO-214AC molded plastic body **Terminals**: leads solderable per MIL-STD-750, Method 2026 Polarity: Color band denotes cathode end Mounting Position: Any Weight: 0.003 ounce, 0.093 grams 0.004 ounce, 0.111 grams SMA(H)



SMA

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

	SYMBOLS	SS12	SS13	SS14	SS15	SS16	SS18	SS110	UNITS
Maximum repetitive peak reverse voltage		20	30	40	50	60	80	100	VOLTS
Maximum RMS voltage		14	21	28	35	42	56	70	VOLTS
Maximum DC blocking voltage	VDC	20	30	40	50	60	80	100	VOLTS
Maximum average forward rectified current at TL(see fig.1)	l(AV)	av) 1.0			Amp				
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	lfsm	40.0		Amps					
Maximum instantaneous forward voltage at 1.0A	VF	0.45 0.55 0.70 0.85		5	Volts				
Maximum DC reverse current Ta=25°C at rated DC blocking voltage Ta=100°C	IR	0.5		mA					
Typical junction capacitance (NOTE 1)	Cı	110 90		pF					
Typical thermal resistance (NOTE 2)		88.0				°C/W			
Operating junction temperature range	TJ,	-65 to +125 -65 to +150			□C				
torage temperature range		-65 to +150			°C				

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C. 2.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas





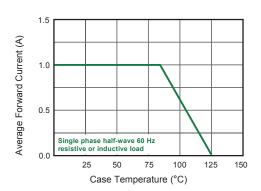


Fig.2 Typical Reverse Characteristics

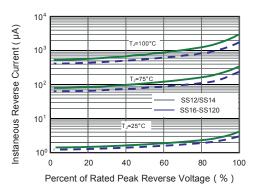


Fig.3 Typical Forward Characteristic

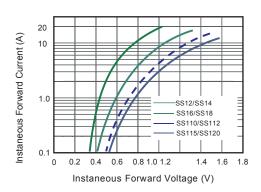


Fig.4 Typical Junction Capacitance

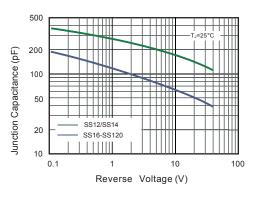


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

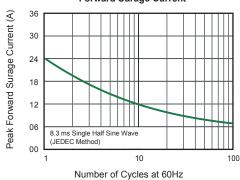
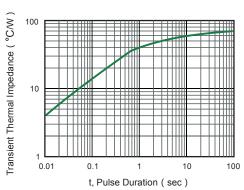


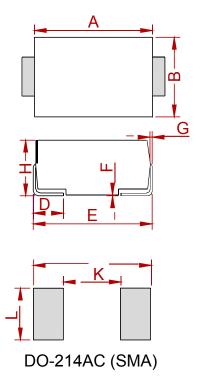
Fig.6- Typical Transient Thermal Impedance







PACKAGE MECHANICAL DATA



	Dimensions					
Ref.	Millin	neters	Inches			
	Min.	Max.	Min.	Max.		
Α	4.25	4.65	0.167	0.183		
В	2.50	2.90	0.098	0.114		
С	1.35	1.65	0.053	0.065		
D	0.76	1.52	0.030	0.060		
Е	4.93	5.28	0.194	0.208		
F	0.051	0.203	0.002	0.008		
G	0.15	0.31	0.006	0.012		
Н	1.98	2.41	0.078	0.095		
J	6.50		0.256			
K		2.30		0.090		
L	1.70		0.067			

REEL SPECIFICATION

P/N	PKG	QTY
SS12-MS/SS110-MS	SMA	2000

Semiconductor

Compiance

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